

## PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT5092890

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YONG LI	04/20/2018
CONG ZHENG	04/23/2018
XIAOYAN WANG	04/23/2018
WENDUO LIU	04/23/2018
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	DIALOG SEMICONDUCTOR INC.
<b>Street Address:</b>	675 CAMPBELL TECHNOLOGY PARKWAY
<b>Internal Address:</b>	SUITE 150
<b>City:</b>	CAMPBELL
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	95008
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16100934
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(949)202-3001
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<b>ATTORNEY DOCKET NUMBER:</b>	52769.67US01
<b>NAME OF SUBMITTER:</b>	JONATHAN W. HALLMAN
<b>SIGNATURE:</b>	/Jonathan W. Hallman/
<b>DATE SIGNED:</b>	08/10/2018
<b>Total Attachments: 2</b>	

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## ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, we

Yong Li of Campbell, California  
Cong Zheng of Campbell, California  
Xiaoyan Wang of Campbell, California  
Wenduo Liu of Campbell, California

hereby sell, assign and transfer to Dialog Semiconductor Inc., a California corporation, having a place of business at 675 Campbell Technology Parkway, Suite 150, Campbell, California 95008, its successors and assigns, the entire right, title and interest throughout the world in my invention in

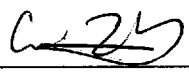
### HYBRID SECONDARY-SIDE REGULATION

for which we filed a United States Patent Application on Jan. 12, 2018 and given Serial Number DS2017-063 and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from me; we agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, their successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request that the United States Patent and Trademark Office issue all patents granted for said invention to the above-named assignee, its successors and assigns.

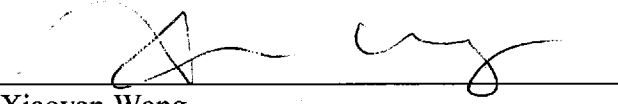
Executed this 20<sup>th</sup> day of April, 2018.

  
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Yong Li

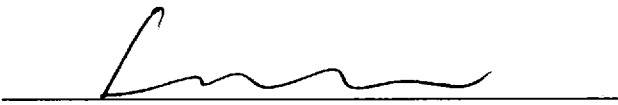
Executed this 23<sup>rd</sup> day of April, 2018.

  
\_\_\_\_\_  
Cong Zheng

Executed this 22<sup>nd</sup> day of April, 2018.

  
Xiaoyan Wang

Executed this 23<sup>rd</sup> day of April, 2018.

  
Wenduo Liu